

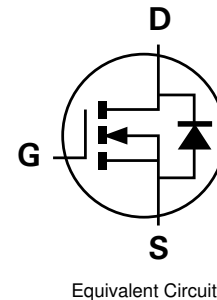
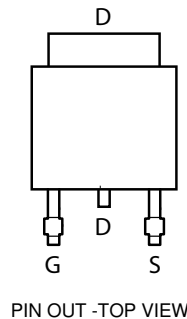
Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$	I_D $T_A = 25^\circ C$
40V	36m Ω @ $V_{GS} = 10V$	12.2A
	61m Ω @ $V_{GS} = 4.5V$	9.4A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- DC-DC Converters
- Power management functions



Features and Benefits

- Low on-resistance
- Fast switching speed
- “Green” component and RoHS compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: TO252-3L
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Matte Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.33 grams (approximate)

Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN4036LK3-13	N4036L	13	16	2,500

Note: 1. Diodes, Inc. defines “Green” products as those which are RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.’s “Green” Policy can be found on our website. For packaging details, go to our website.

Marking Information



$\text{D}|||$ = Manufacturer's Marking
 N4036L = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Year (ex: 09 = 2009)
 WW = Week (01 - 53)

Maximum Ratings @T_A = 25°C unless otherwise specified

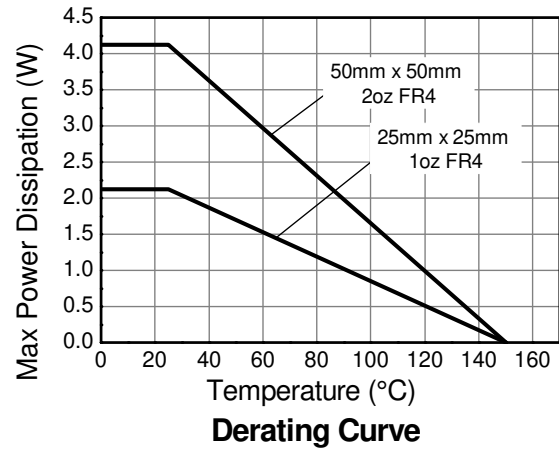
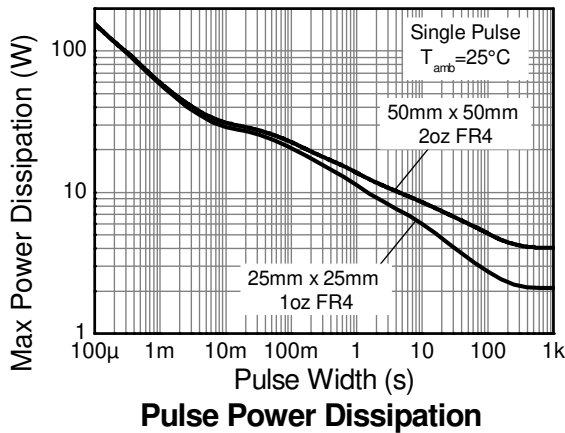
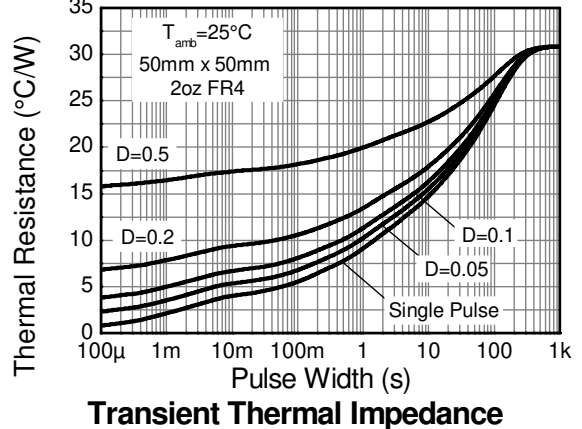
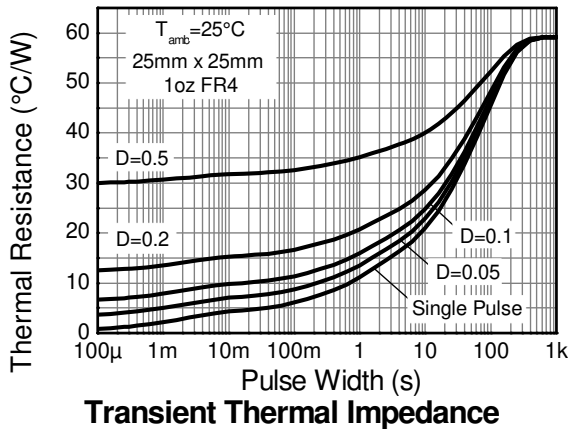
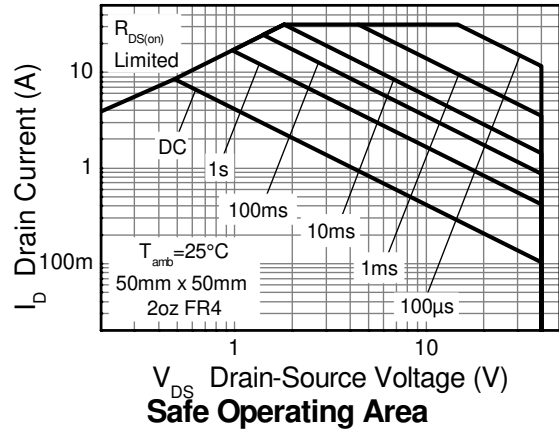
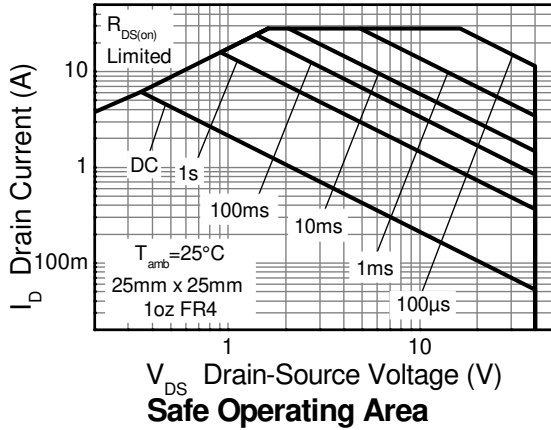
Characteristic		Symbol	Value	Unit	
Drain-Source voltage		V _{DSS}	40	V	
Gate-Source voltage		V _{GS}	±20	V	
Continuous Drain current	V _{GS} = 10V	I _D	(Note 2)	12.2	A
			(Note 4)	9.7	
			T _A = 70°C (Note 4)	8.5	
Pulsed Drain current		I _{DM}	31.7	A	
Continuous Source current (Body diode)		I _S	10.4	A	
Pulsed Source current (Body diode)		I _{SM}	31.7	A	

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Power dissipation Linear derating factor	(Note 3)	P _D	4.12	W mW/°C
	(Note 4)		33	
	(Note 6)		8.49	
	(Note 3)		67.9	
Thermal Resistance, Junction to Ambient	(Note 3)	R _{θJA}	2.12	°C/W
	(Note 4)		16.9	
	(Note 6)		30.3	
Thermal Resistance, Junction to Lead	(Note 7)	R _{θJL}	14.7	°C/W
Operating and storage temperature range		T _J , T _{STG}	59.0	
			3.1	°C

- Notes:
- AEC-Q101 V_{GS} maximum is ±16V.
 - For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 - Same as note 3, except the device is measured at t ≤ 10 sec.
 - Same as note 3, except the device is pulsed with D = 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.
 - For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 - Thermal resistance from junction to solder-point (at the end of the drain lead).

Thermal Characteristics

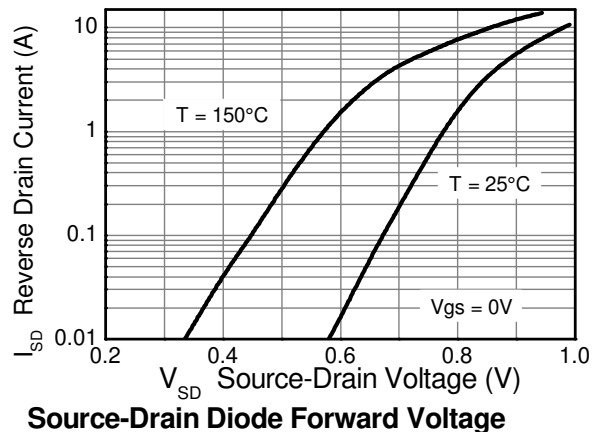
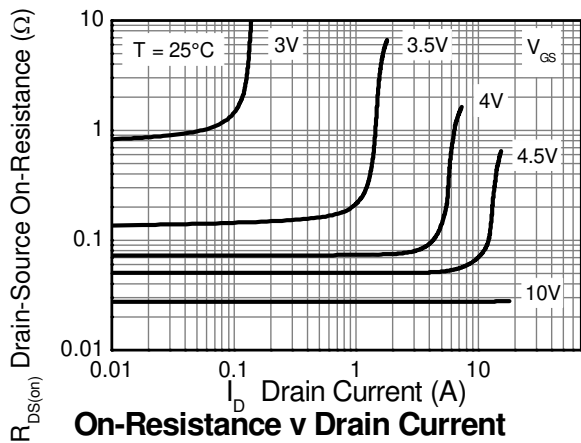
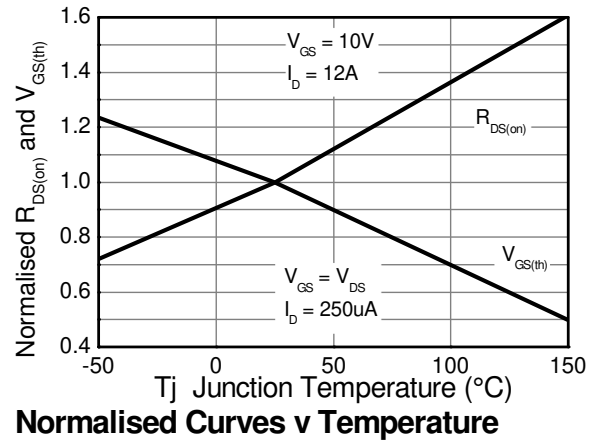
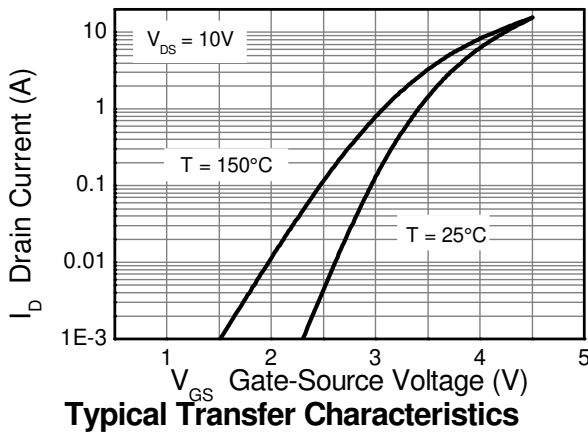
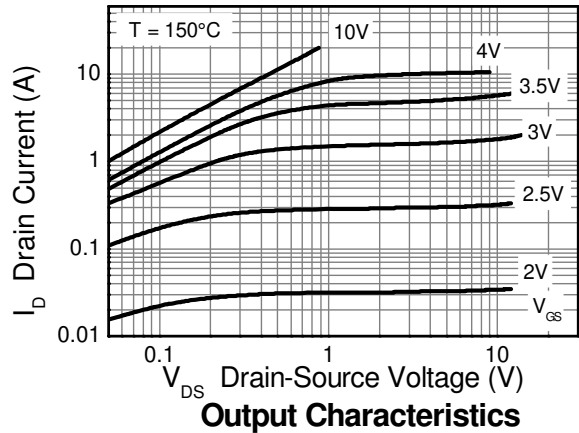
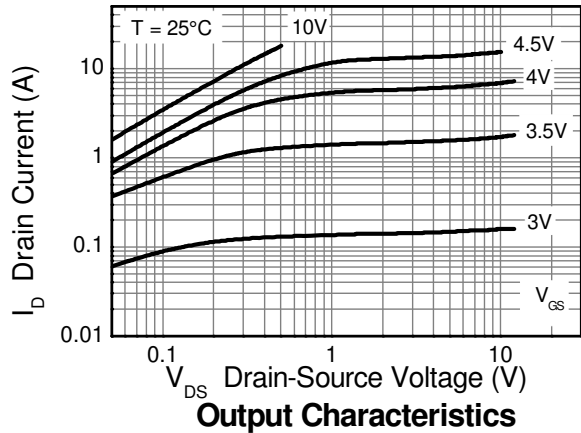


Electrical Characteristics @T_A = 25°C unless otherwise specified

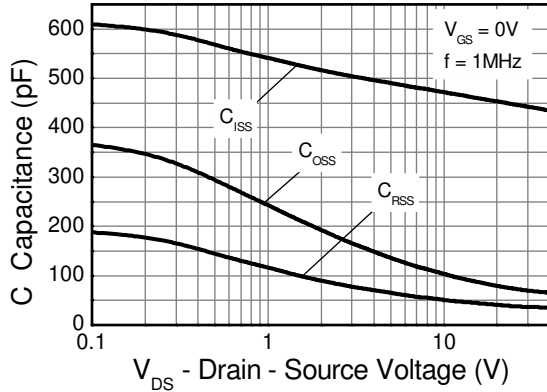
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	40	—	—	V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	—	—	0.5	μA	V _{DS} = 40V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	1.0	—	3.0	V	I _D = 250μA, V _{DS} = V _{GS}
Static Drain-Source On-Resistance (Note 8)	R _{DS(on)}	—	0.026	0.036	Ω	V _{GS} = 10V, I _D = 12A
			0.049	0.061		V _{GS} = 4.5V, I _D = 6A
Forward Transconductance (Notes 8 & 9)	g _{fs}	—	19.6	—	S	V _{DS} = 15V, I _D = 12A
Diode Forward Voltage (Note 8)	V _{SD}	—	0.96	1.1	V	I _S = 12A, V _{GS} = 0V
Reverse recovery time (Note 9)	t _{rr}	—	112	—	ns	I _S = 12A, di/dt = 100A/μs
Reverse recovery charge (Note 9)	Q _{rr}	—	926	—	nC	
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iSS}	—	453	—	pF	V _{DS} = 20V, V _{GS} = 0V f = 1MHz
Output Capacitance	C _{oss}	—	79.1	—	pF	
Reverse Transfer Capacitance	C _{rSS}	—	40.5	—	pF	
Total Gate Charge (Note 10)	Q _g	—	4.9	—	nC	V _{GS} = 4.5V
Total Gate Charge (Note 10)	Q _g	—	9.2	—	nC	V _{GS} = 10V
Gate-Source Charge (Note 10)	Q _{gs}	—	1.7	—	nC	
Gate-Drain Charge (Note 10)	Q _{gd}	—	2.7	—	nC	
Turn-On Delay Time (Note 10)	t _{D(on)}	—	3.2	—	ns	V _{DD} = 20V, V _{GS} = 10V I _D = 12A, R _G ≅ 6.0Ω
Turn-On Rise Time (Note 10)	t _r	—	11.7	—	ns	
Turn-Off Delay Time (Note 10)	t _{D(off)}	—	11.6	—	ns	
Turn-Off Fall Time (Note 10)	t _f	—	9.5	—	ns	

- Notes:
8. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%
 9. For design aid only, not subject to production testing.
 10. Switching characteristics are independent of operating junction temperatures.

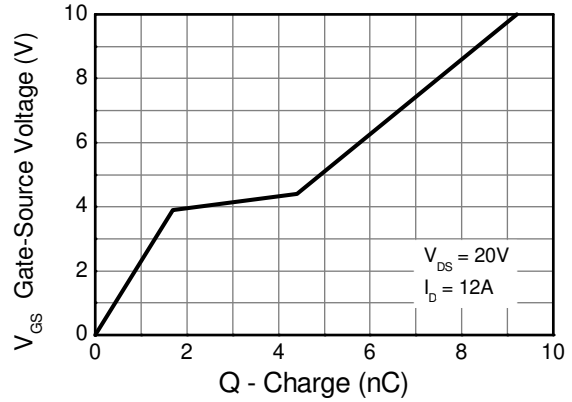
Typical Characteristics



Typical Characteristics - continued

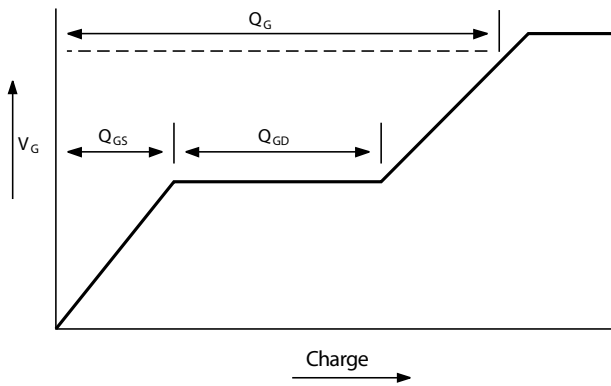


Capacitance v Drain-Source Voltage

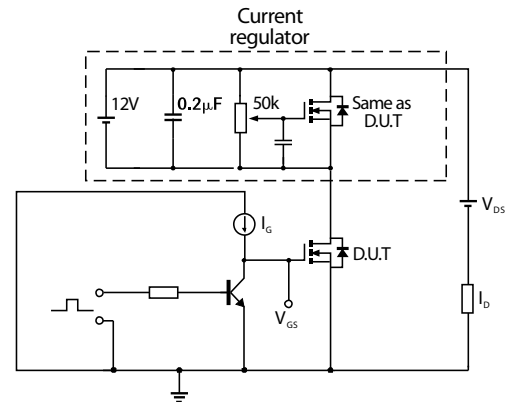


Gate-Source Voltage v Gate Charge

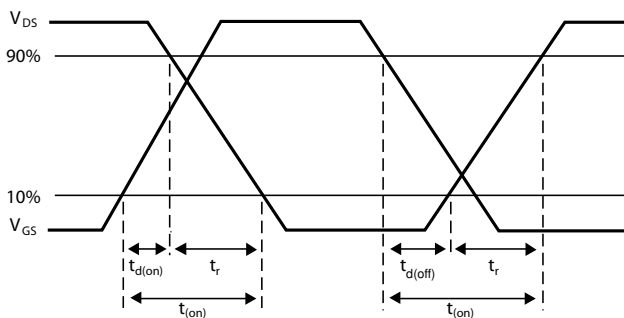
Test Circuits



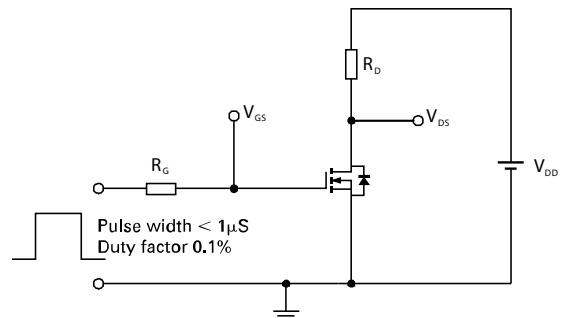
Basic gate charge waveform



Gate charge test circuit

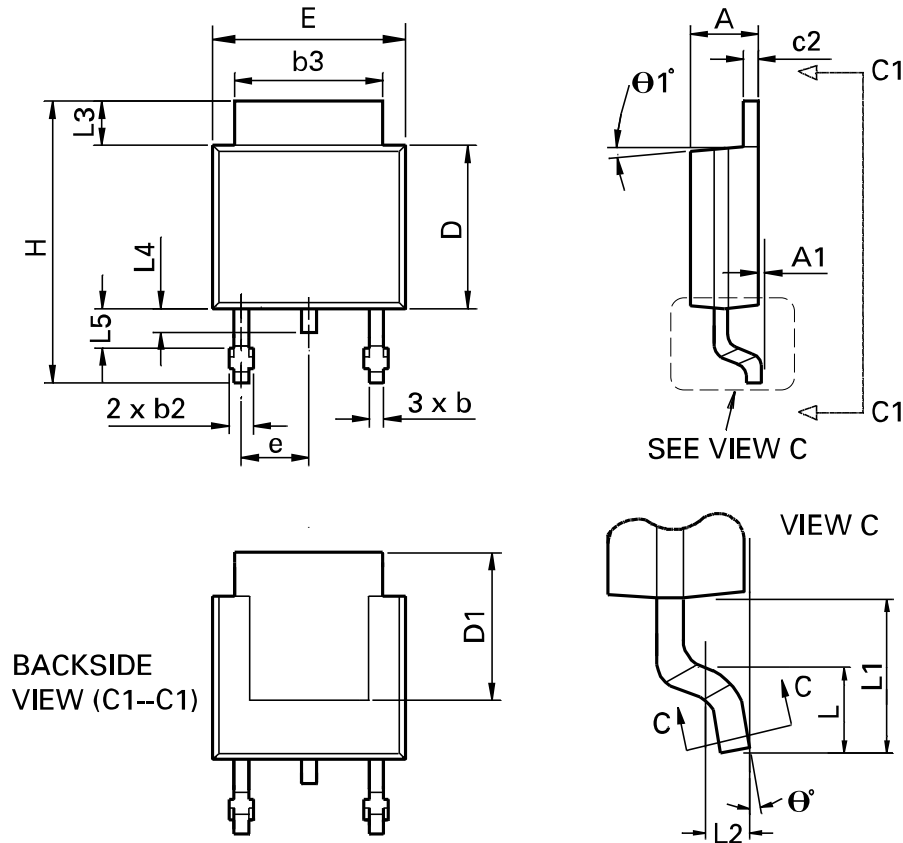


Switching time waveforms



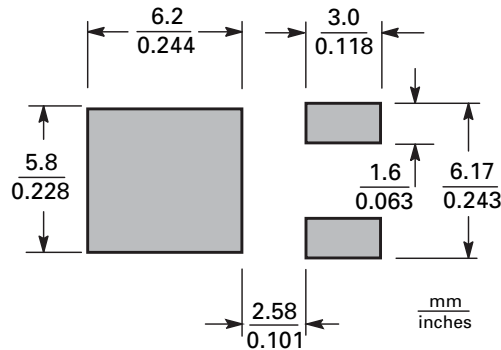
Switching time test circuit

Package Outline Dimensions



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
A	0.086	0.094	2.18	2.39	e	0.090 BSC		2.29 BSC	
A1	-	0.005	-	0.127	H	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
c	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	θ_1°	0°	10°	0°	10°
E	0.250	0.265	6.35	6.73	θ°	0°	15°	0°	15°
E1	0.170	-	4.32	-	-	-	-	-	-

Suggested Pad Layout



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